

20V P-Channel Enhancement Mode MOSFET

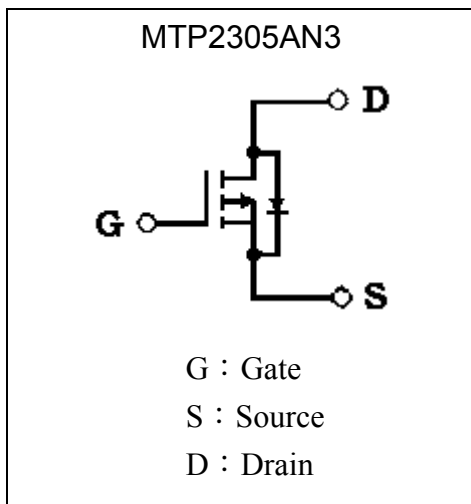
MTP2305AN3

BV_{DSS}	-20V
$I_D@V_{GS}=-4.5V, T_A=25^{\circ}C$	-3.4A
$R_{DS(on)(TYP)}@V_{GS}=-4.5V, I_D=-2.8A$	79mΩ
$R_{DS(on)(TYP)}@V_{GS}=-2.5V, I_D=-2A$	116mΩ

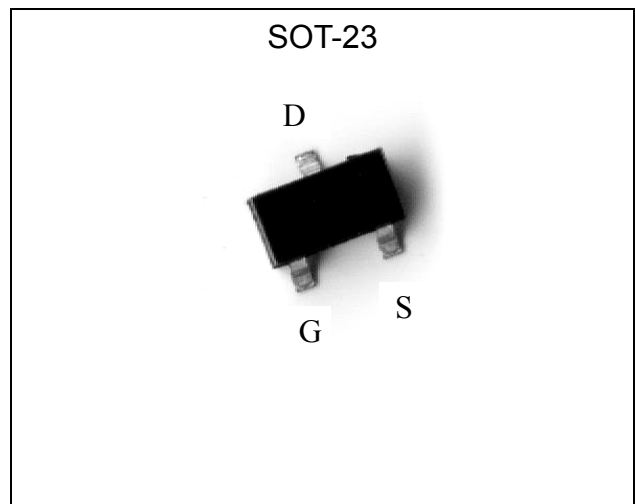
Features

- Advanced trench process technology
- High density cell design for ultra low on resistance
- Excellent thermal and electrical capabilities
- Compact and low profile SOT-23 package
- Pb-free lead plating and halogen-free package

Equivalent Circuit

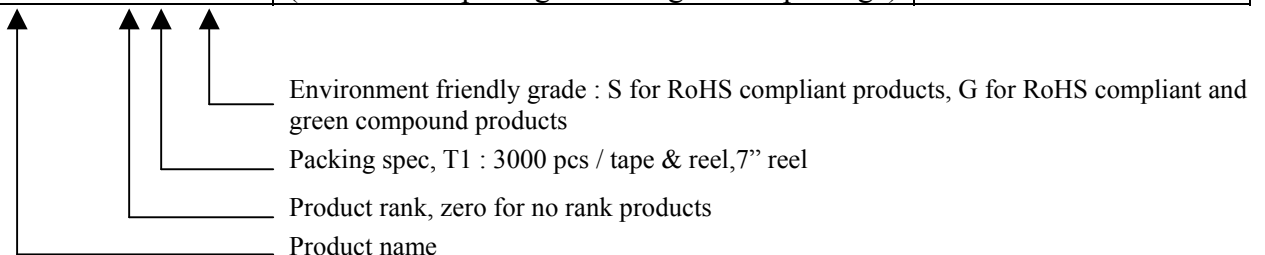


Outline



Ordering Information

Device	Package	Shipping
MTP2305AN3-0-T1-G	SOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel





Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	VDS	-20	V
Gate-Source Voltage	VGS	±8	V
Continuous Drain Current @TA=25°C, VGS=-4.5V	ID	-3.4	A
Continuous Drain Current @TA=70°C, VGS=-4.5V		-2.7	
Pulsed Drain Current	IDM	-10	
Maximum Power Dissipation	PD	Ta=25°C	1.38 (Note)
		Ta=70°C	0.88 (Note)
Operating Junction and Storage Temperature Range	Tj ; Tstg	-55~+150	°C

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient(PCB mounted)	Rth,ja	90 (Note)	°C/W
Lead Temperature, for 5 second soldering(1/8" from case)	TL	260	°C

Note : Surface mounted on 1 in ²FR-4 board with 2 oz. copper, t ≤ 5sec; 270 °C/W when mounted on minimum copper pad.

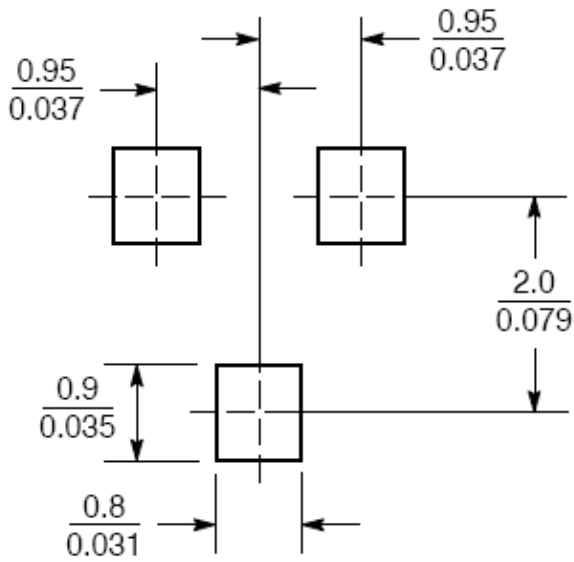
Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BVDSS	-20	-	-	V	VGS=0, ID=-250μA
VGS(th)	-0.45	-	-	V	VDS=VGS, ID=-250μA
IGSS	-	-	±100	nA	VGS=±8V, VDS=0
IDSS	-	-	-1	μA	VDS=-16V, VGS=0
*RDS(ON)	-	79	108	mΩ	ID=-2.8A, VGS=-4.5V
	-	116	150		ID=-2A, VGS=-2.5V
*GFS	-	6.3	-	S	VDS=-5V, ID=-2.8A
Dynamic					
Ciss	-	446	-	pF	VDS=-10V, VGS=0, f=1MHz
Coss	-	57	-		
Crss	-	52	-		
td(ON)	-	9.2	20	ns	VDD=-10V, ID=-1A, RL=6Ω, VGEN=-4.5V, RG=6Ω
tr	-	7.3	60		
td(OFF)	-	38	50		
tf	-	12	20		
Qg	-	3	10	nC	VDS=-10V, ID=-3A, VGS=-2.5V,
Qgs	-	0.8	-		
Qgd	-	1.1	-		

Source-Drain Diode					
I_S	-	-	-1.6	A	-
V_{SD}	-	-0.86	-1.2	V	$V_{GS}=0V, I_S=-1.6A$
t_{rr}^*	-	30	-	ns	$I_F=-3A, dI_F/dt=100A/\mu s$
Q_{rr}^*	-	25	-	nC	

*Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Recommended Soldering Footprint

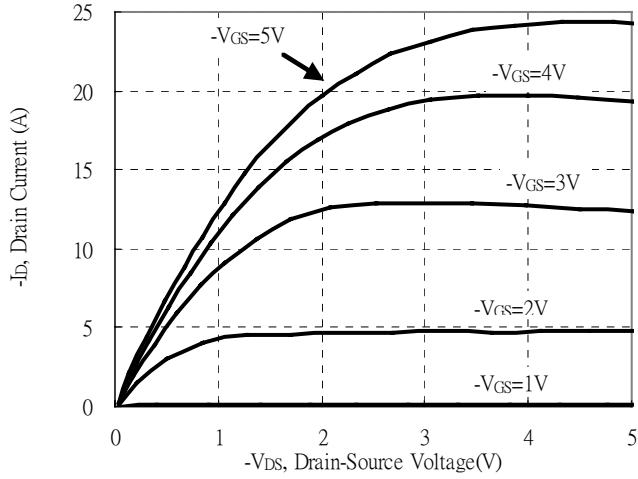


Unit : $\frac{mm}{inches}$

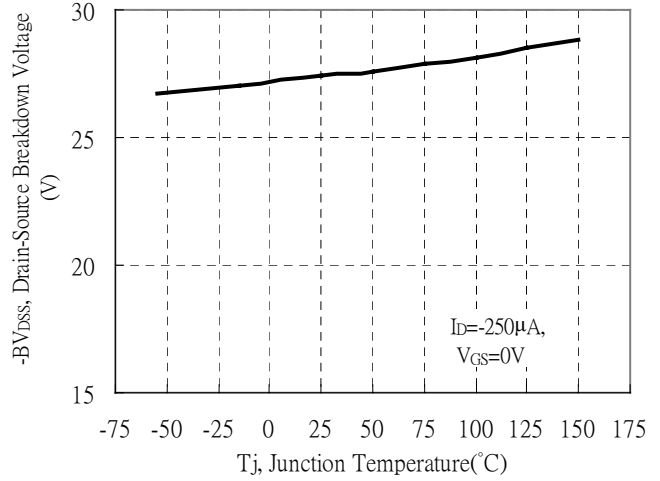


Typical Characteristics

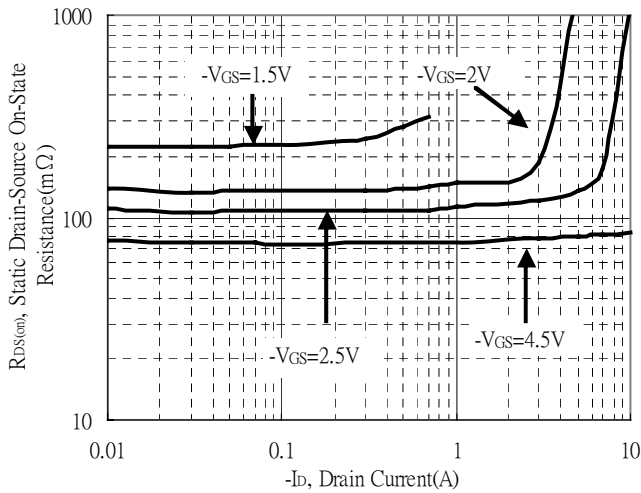
Typical Output Characteristics



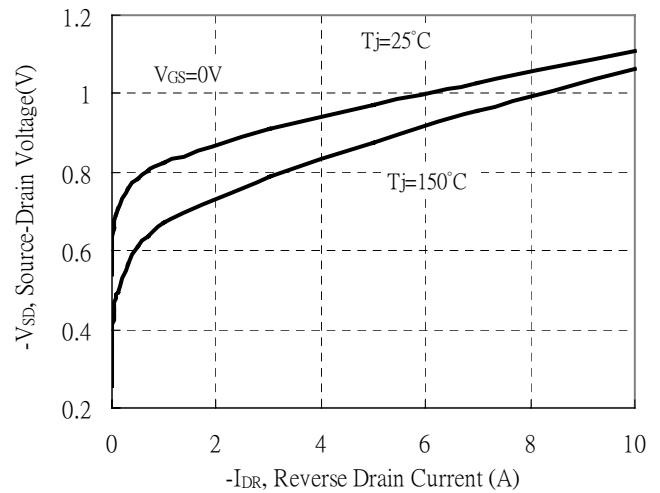
Brekdown Voltage vs Ambient Temperature



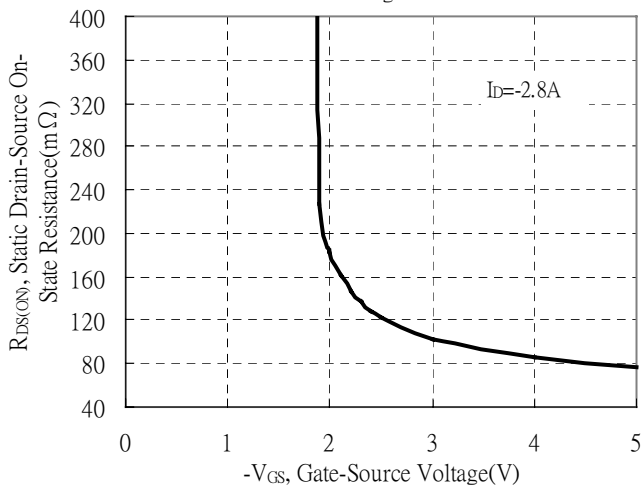
Static Drain-Source On-State resistance vs Drain Current



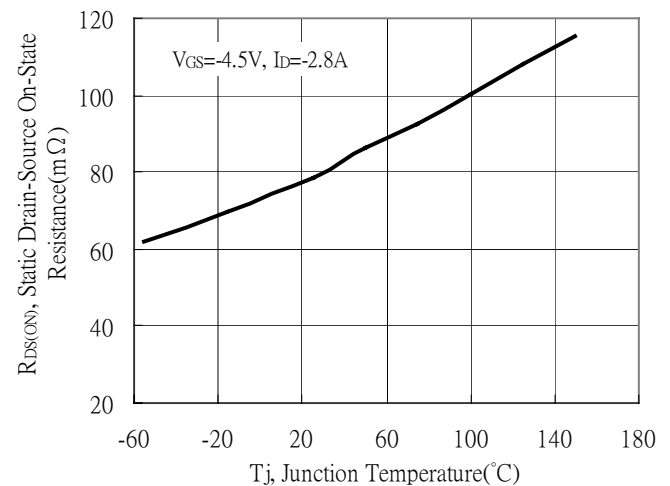
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

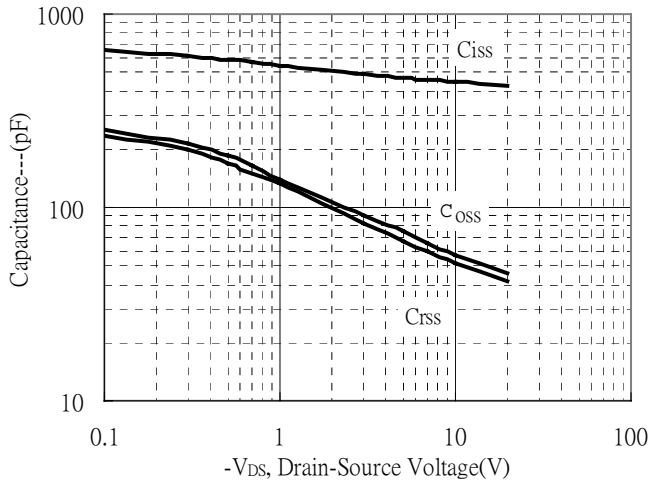


Drain-Source On-State Resistance vs Junction Temperature

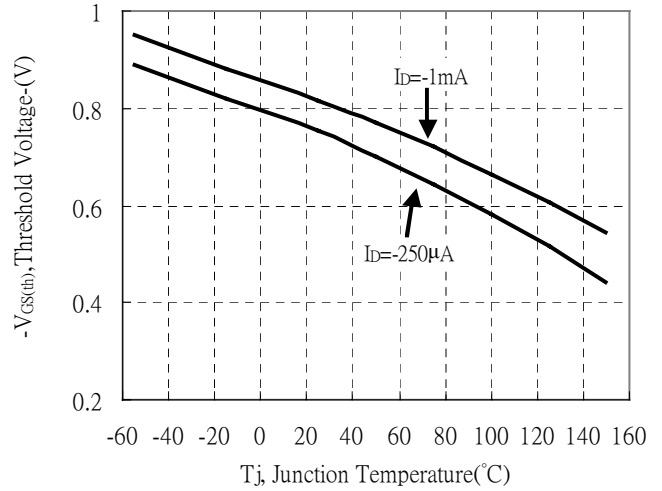


Typical Characteristics(Cont.)

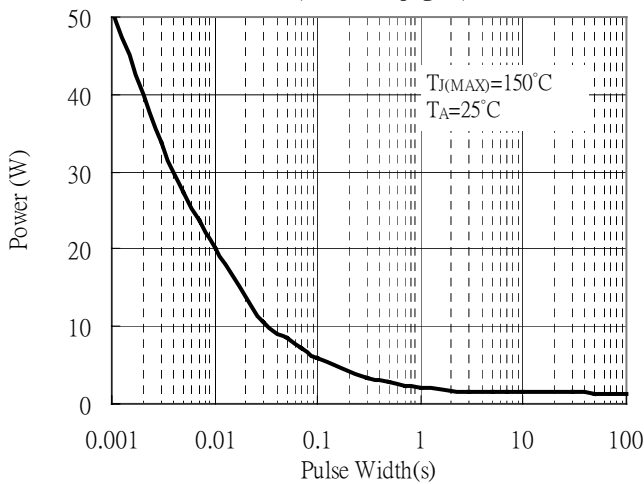
Capacitance vs Drain-to-Source Voltage



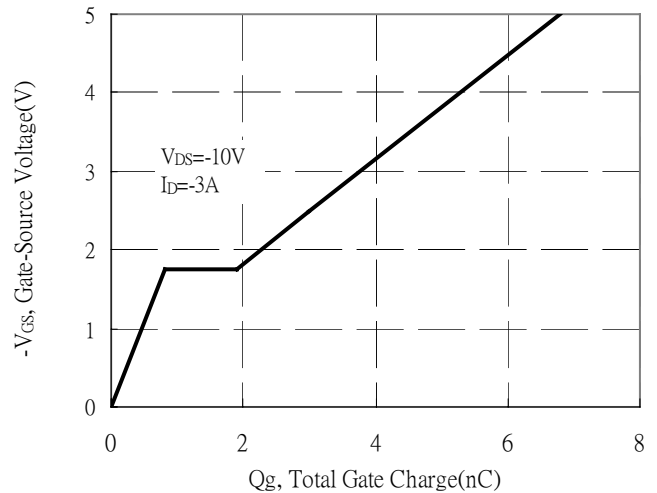
Threshold Voltage vs Junction Temperature



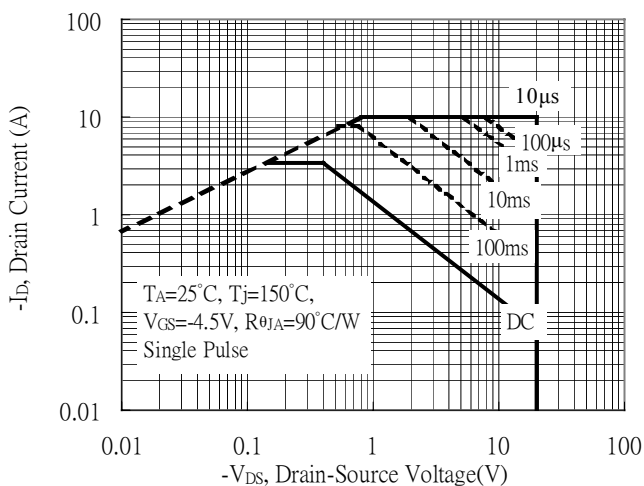
Single Pulse Power Rating, Junction to Ambient
 (Note 1 on page 2)



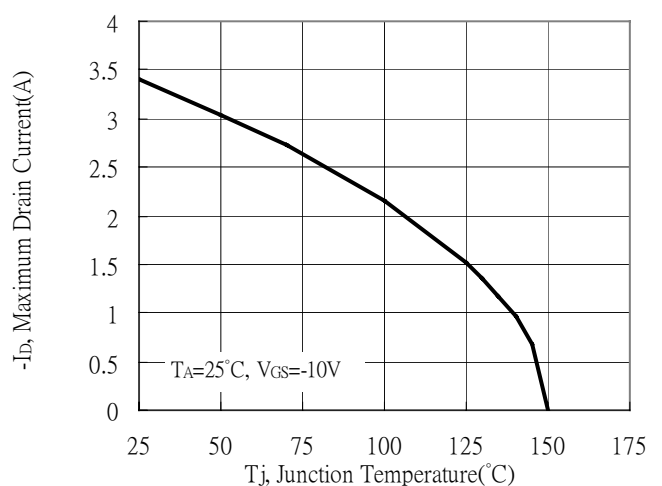
Gate Charge Characteristics



Maximum Safe Operating Area



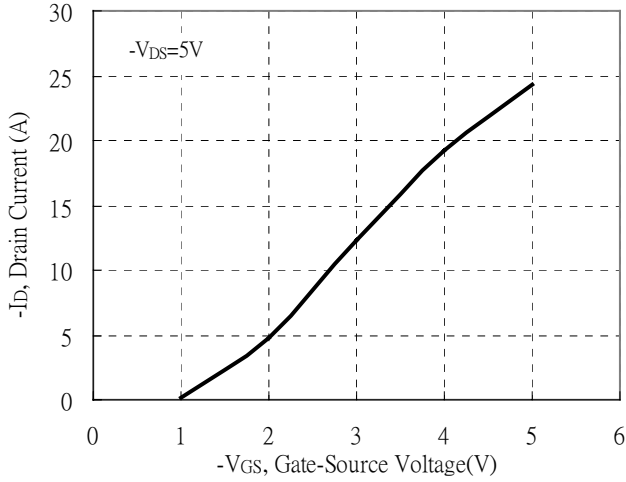
Maximum Drain Current vs Junction Temperature



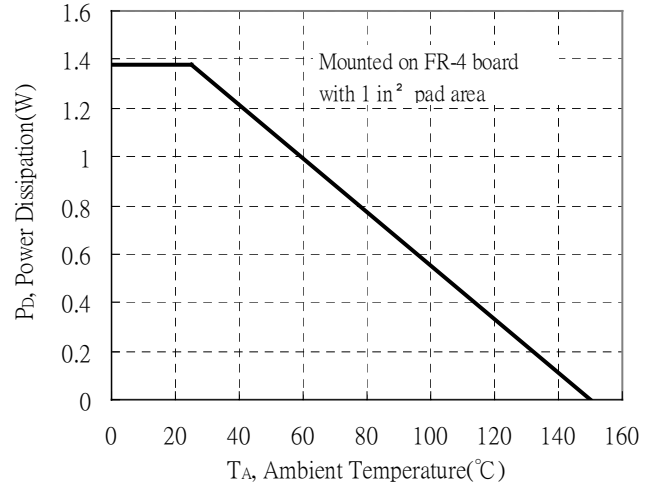


Typical Characteristics(Cont.)

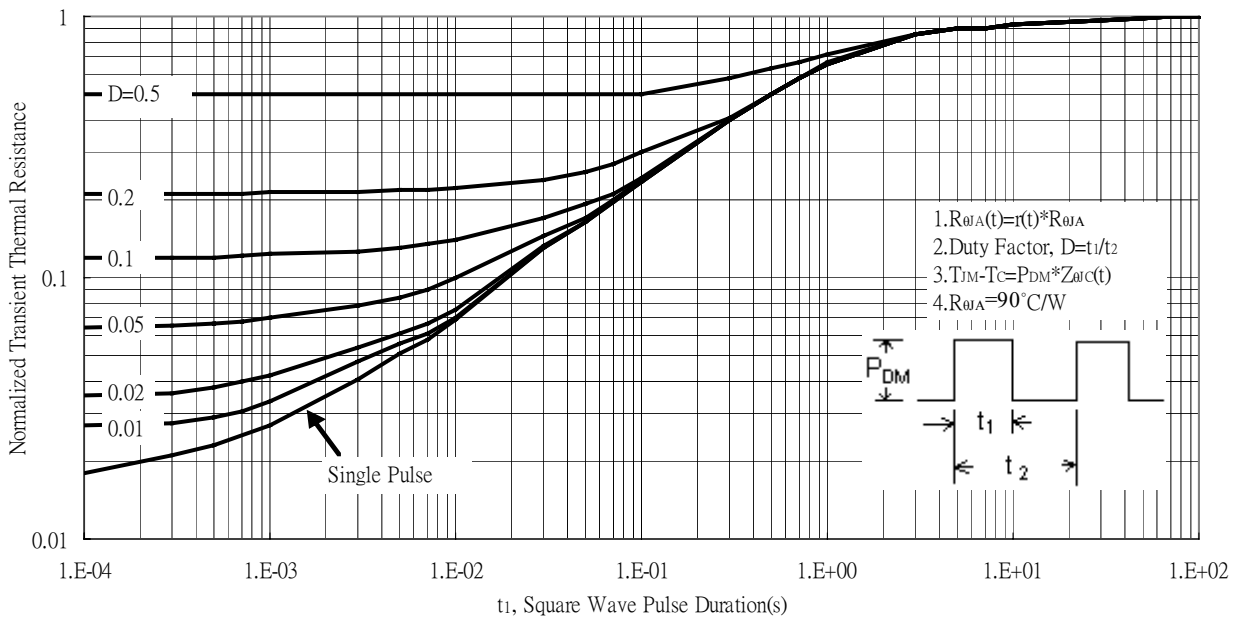
Typical Transfer Characteristics



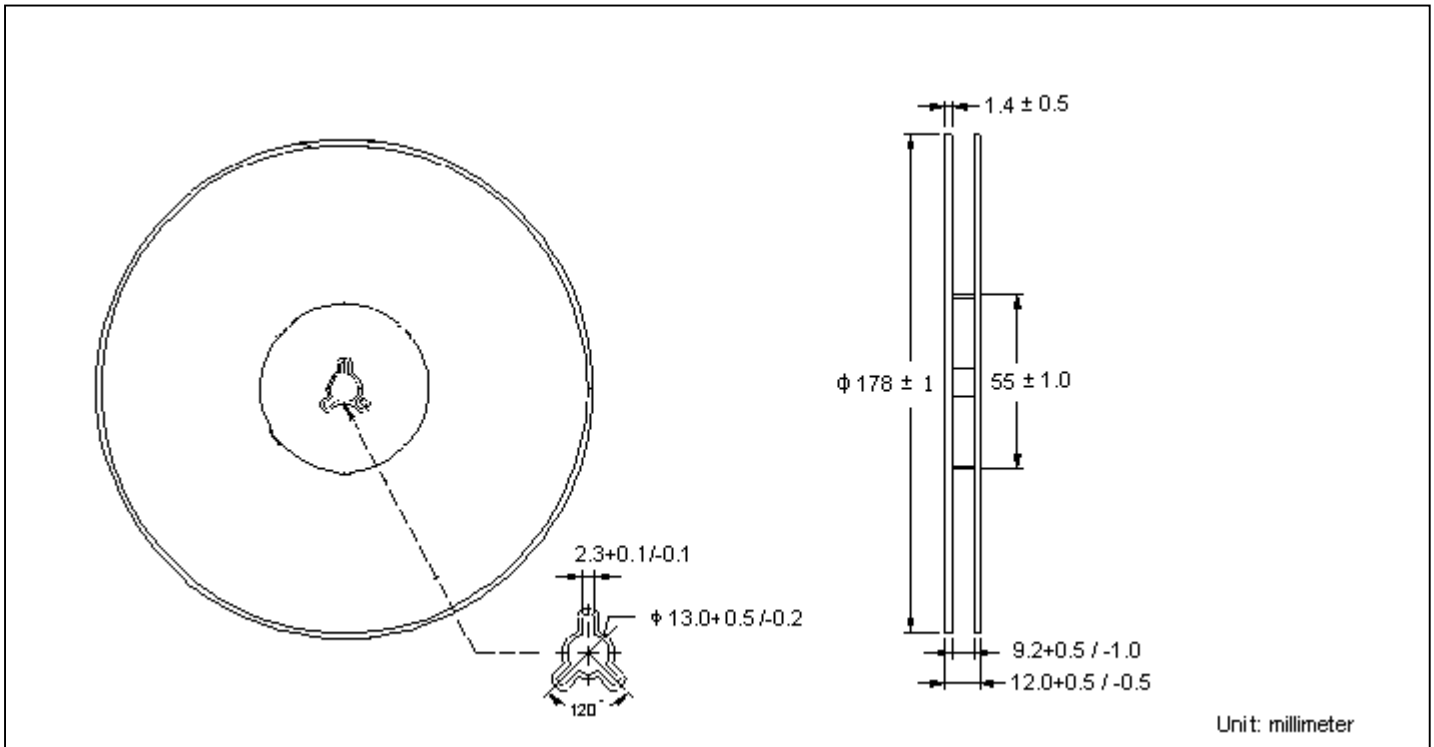
Power Derating Curve



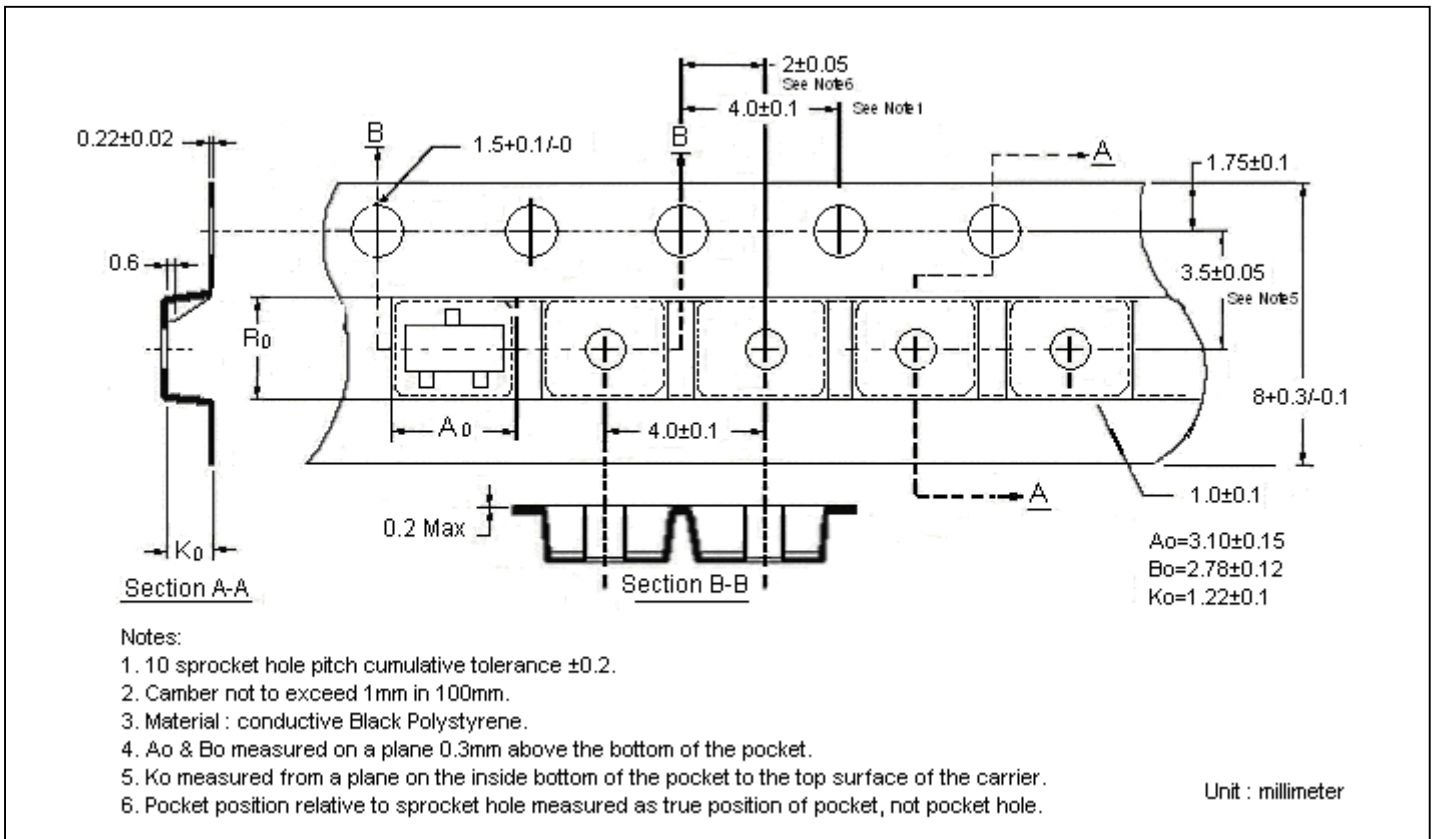
Transient Thermal Response Curves



Reel Dimension



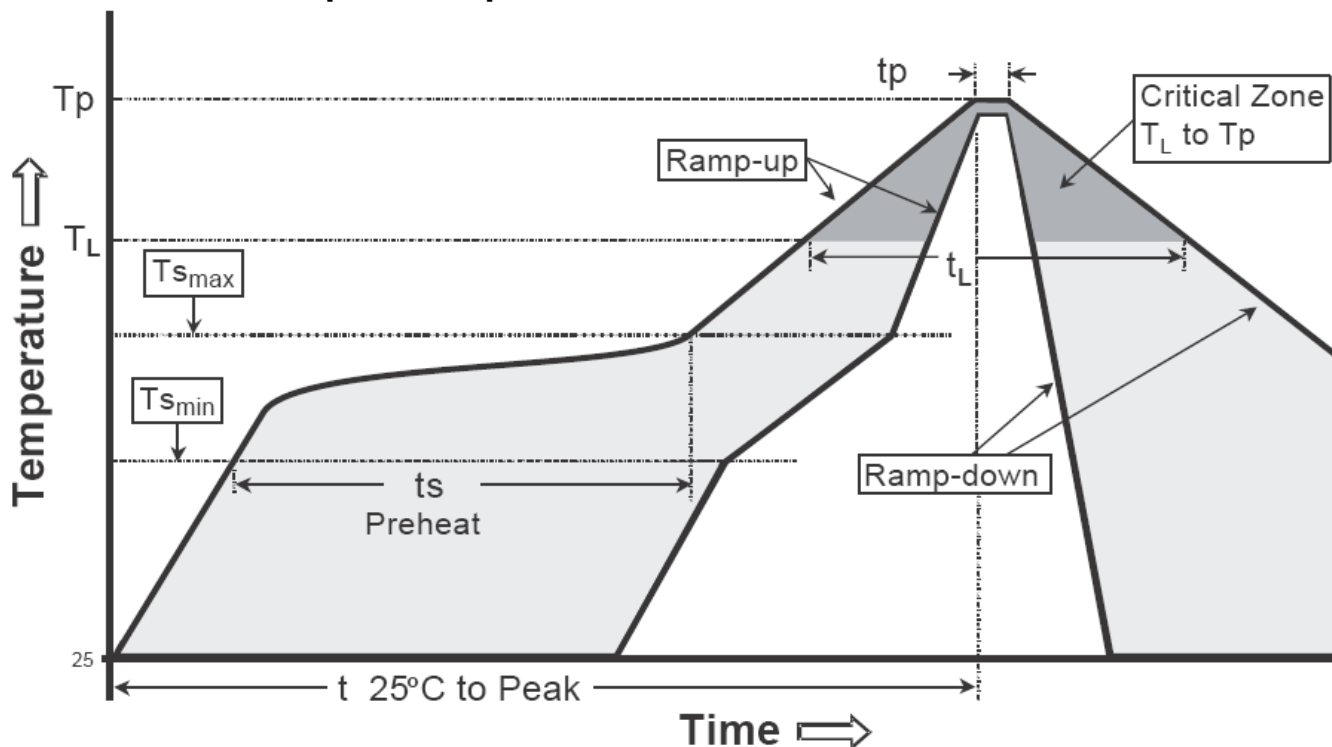
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

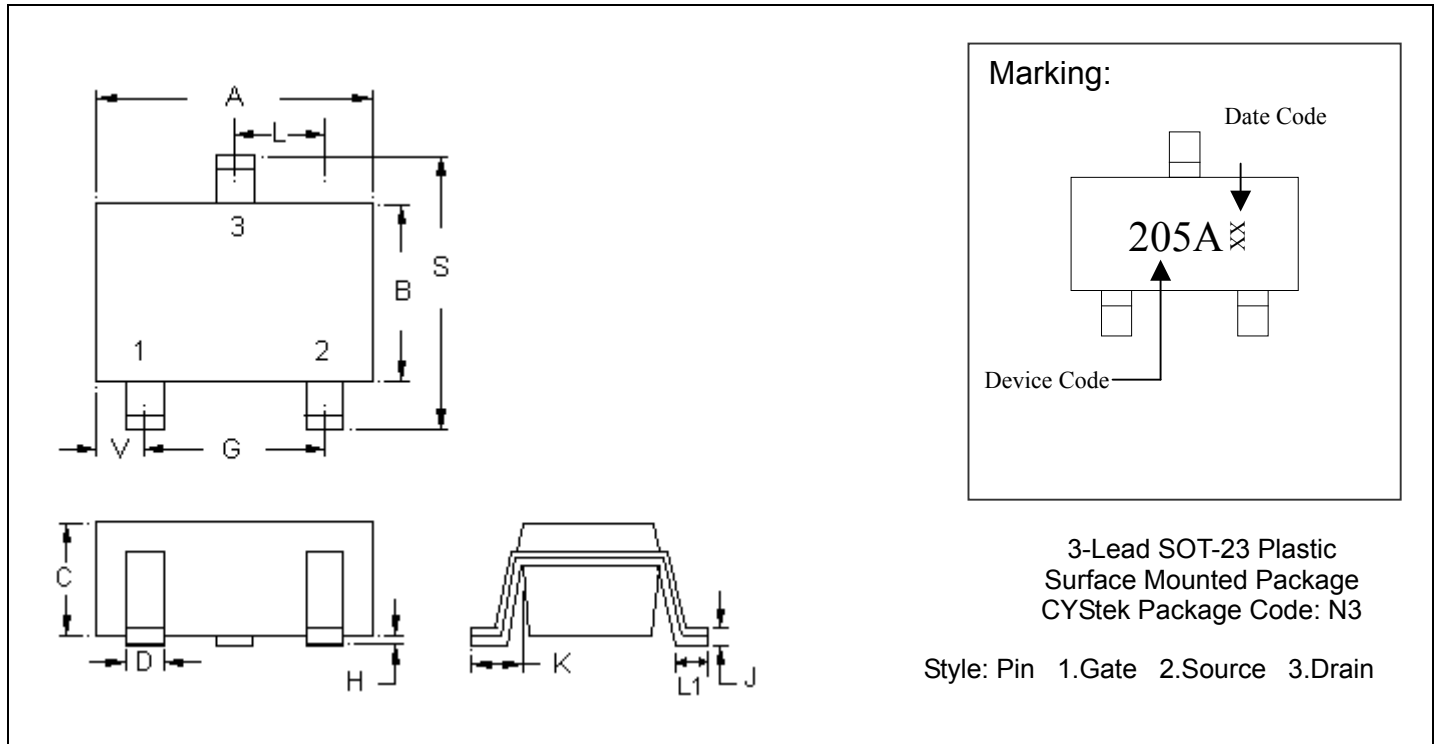
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10	L1	0.0118	0.0197	0.30	0.50

- Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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